Abstracts

Microwave Characterization of Flip-Chip MMIC Interconnections

R.B. Marks, J.A. Jargon, C.K. Pao and C.P. Wen. "Microwave Characterization of Flip-Chip MMIC Interconnections." 1995 MTT-S International Microwave Symposium Digest 95.3 (1995 Vol. III [MWSYM]): 1463-1466.

We report accurate on-wafer measurements of transmission lines on flip-chip coplanar-waveguide MMICS. The effects are difficult to predict theoretically, and, without custom standards and unique calibration software, measurements would be intractable. The results are applicable to the development of an accurate CAD database. We also report and apply a new technique for the measurement of transmission line capacitance.

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